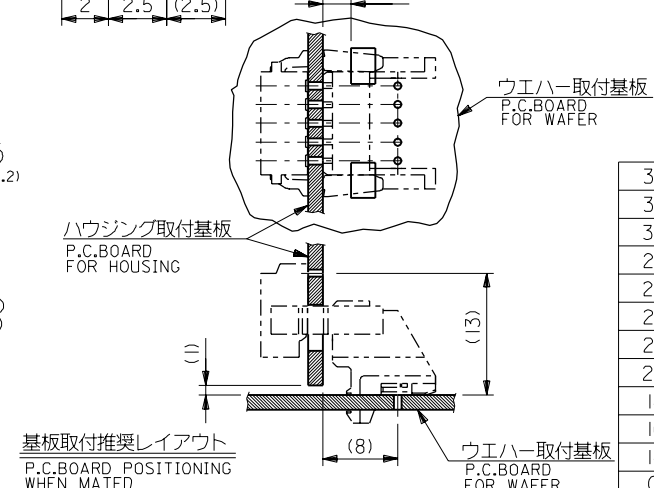
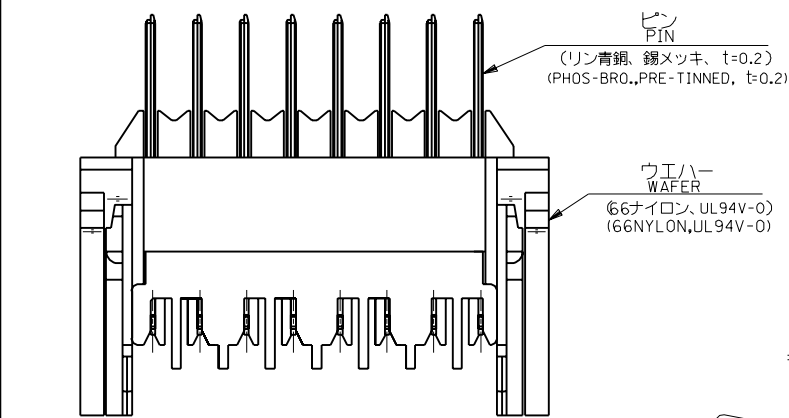
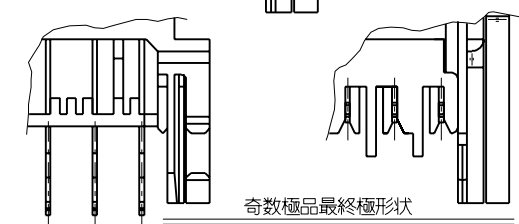


基板取付穴推奨寸法 (マウント面) (基板厚: 1.6)
 RECOMMENDED P.C. BOARD HOLE DIM.
 (MOUNT SURFACE) (t=1.6)

注記
 NOTE
 1. 嵌合相手: 52170-***10
 MATE WITH 52170-***10



34	31	28	53114-1510	15
32	29	26	-1410	14
30	27	24	-1310	13
28	25	22	-1210	12
26	23	20	-1110	11
24	21	18	-1010	10
22	19	16	-0910	9
20	17	14	-0810	8
18	15	12	-0710	7
16	13	10	-0610	6
14	11	8	53114-0510	5
C	B	A	ENG. NO.	極致 CKT.



THE LAST CKT VIEW OF ODD CKT CONN.

角度 ANGLE	±3°
30以上 OVER	+0.3
10以上 30未満 UNDER	+0.25
10未満 UNDER	+0.2
角公差 GENERAL TOLERANCES	
記号 LTR	変更内容 REVISION RECORD
再作図 REDRAWN	(JC6167)
S.M. H.H.	
DR. DATE	'95/09/11

材料 MATERIAL	図中参照 SEE DRAWING
仕上げ FINISH	— / —
適用電線範囲 WIRE RANGE	— / —
被覆外径 INS. RANGE	— / —
DRAWN BY '95/09/11	CHK'D BY '95/09/11
S.MATSUZAKI	Y.M. H.HIRAMOTO
APP'D BY '95/09/11	尺度 SCALE 5 : 1
M.FUKUSHIMA	

材料 MATERIAL		図中参照 SEE DRAWING
仕上げ FINISH		— / —
適用電線範囲 WIRE RANGE		— / —
被覆外径 INS. RANGE		— / —
DRAWN BY '95/09/11		CHK'D BY '95/09/11
S.MATSUZAKI		Y.M. H.HIRAMOTO
APP'D BY '95/09/11		尺度 SCALE 5 : 1
M.FUKUSHIMA		
MATERIAL		図中参照 SEE DRAWING
モレックス MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社		
REVISE ONLY ON CAD SYSTEM		
TITLE 名称		2.0 FLOATING BOARD TO BOARD CONN. WAFER ASS'Y
DWG. NO.		SD-53114-***10
REV		C